

FIRST!

by FMD

**Fast
Innovation through
Research in
Semiconductor
Technologies**

The new flagship event for microelectronics in Europe



What:

Two-day high-level event designed as a trend radar and a strategic meeting point for the European microelectronic industry

When:

September 30 – October 01, 2026

Where:

Berlin

Who:

over **500 participants** expected

Language:

English

Why:

Strategically shaping Europe's future with microelectronics



FIRST as Europe's leading trend forum for microelectronics



Positioning

- **FIRST** is bridging the gap between global summits (e.g. ITF World by imec, Leti Innovation Days) and technical conferences/trade shows (e.g. EuMW, ECTC, PCIM, Sensor+Test, Semicon Europe, Electronica)
- **FIRST** is deliberately **not a technical conference**, but rather a **trend radar and a strategic meeting point** for the European microelectronic industry

Benefits for decision-makers

- **Trends:** Identifying early on which technologies and markets will shape the future
- **Curated content:** Reducing complexity and focusing on industry-relevant developments
- **Orientation:** Translating trends into actionable strategies and decisions
- **Community:** Enabling networking with relevant stakeholders from industry, research and politics

Strategic added value

- **Direct influence:** Participating in discussions on industry transformations
- **Exclusive insights:** A compact overview of disruptive trends, market needs and regulatory developments
- **High-level connections:** Networking to identify strategic partnerships and alliances
- **Positioning as a thought leader:** Presentation of innovation strategies to an exclusive audience of decision-makers

What does FIRST stand for?



1. Early trend identification for users

- Technology trends – where microelectronics is headed?
- Ecosystem developments – how applications can benefit
- Strategic roadmaps (Europe, Germany, global players)

3. Orientation for strategic decision-making

- For industry (CTOs, R&D managers, senior specialists, BD)
- For policymakers, funding agencies and program managers
- For education and research (universities, RTOs, study directors)

2. Curated overview for more direction in the ecosystem

- Functional roadmaps – which technologies will be available when
- Microelectronics as an enabler through system integration
- Contributions from leading European companies in the industry

4. Neutral networking platform for key players

- Industry, associations, politics, research
- Competitors and partners together on equal terms

Who is FIRST for and what does it offer?



FIRST brings together business, politics and research stakeholders and provides a platform for discussion and strategic setting for innovation in microelectronics in Europe.

What is missing today: A place for orientation and strategic coordination instead of individual perspectives.

For the industry

- Early orientation on emerging **technological trends**
- **Reliable roadmaps** instead of uncertainty
- **Fast transfer paths** from research to marketable applications

For the policymakers

- Basis for **future-oriented funding strategies**
- **Strategic calls for proposals** instead of fragmented programs
- **Clear regulatory guidelines** for industrial implementation in Europe

For education and research

- Definition of the **key competencies of tomorrow**
- From **system expertise & chip design** to **advanced manufacturing & integration**
- Targeted further development of **research facilities and educational programs**

Agenda overview

Day 1: Microelectronics for the future of Europe

Strategy and policy: How can we shape Europe's future with microelectronics?

Contribution to the EU strategy and Germany's high-tech agenda on enhancing Europe's technological resilience

Innovation ecosystems and technological trends:

Interpretation of global technology trends and their relevance for European strategies and roadmaps

Transfer to the market:

Discussions and panels on "Lab-to-Industry" – how innovations can be brought into production more quickly

Advanced packaging as an emerging technology for Europe:

Transforming microelectronics into applications

Design infrastructure for European companies:

A crucial building block for the advanced semiconductor ecosystem

Cross-sector cooperation:

Exchange between industry, research and politics for the implementation of European initiatives

Day 2: EU Chips Act & APECS Pilot Line

European semiconductor ecosystem: Access to the pilot lines

How pilot lines strengthen European value chains in the semiconductor sector through cooperation and innovation

Focus on the APECS pilot line:

Practical insights into chiplet technologies, STCO, front-end, QMI and industrial applications

Masterclasses:

Exclusive insights into chiplet manufacturing, design infrastructure, advanced packaging and STCO

Talent, skills and workforce:

Strategic panel discussion on the non-technical success factors of semiconductor excellence

High-level speakers



Henna Virkkunen

Executive Vice-President of the European Commission for Tech Sovereignty, Security and Democracy *[inquired]*



Dorothee Bär

Federal Minister of Research, Technology and Space *[inquired]*



Holger Hanselka

President of the Fraunhofer-Gesellschaft



Peter Leibinger

President of the Federation of German Industries (BDI) and Chairman of the Supervisory and Administrative Board of Trumpf *[inquired]*

Europe & Germany: Strategic Alignment in Action | Day 1, 30.9.2026



9:30 – 11:00 | Inauguration of the APECS Pilot Line & Grand Opening Panel (open access)

“Shaping Europe’s Future with Semiconductors: Trends, Roadmaps, and Strategic Alignment”

High-level representatives from politics and industry discuss how Europe’s strategic microelectronics agenda can be consistently implemented and closely aligned with national initiatives in Germany.

11:00 – 12:15 | High-Level Roundtable (by invitation only, max. 15 participants)

“Europe’s Strategic Agenda at the Core – Ensuring Complementarity with Germany’s High-Tech Agenda”

Following the public panel discussion a closed-door roundtable will be convened with a select group of senior representatives from research, politics and industry. This confidential setting is intended to enable a strategic exchange on ensuring complementarity and coherence of European initiatives and Germany’s high-tech agenda in microelectronics — in particular, regarding pilot lines, investment leverage, innovation scaling and regulatory alignment within the European Union.

12:15 – 13:30 | Executive Lunch (by invitation only, max. 40 participants)

Additional selected representatives from politics, industry and research will join the roundtable participants for an executive lunch, offering further opportunity for dialogue and bilateral discussions.

FIRST Location

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FIRST:
A warm welcome



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